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t	he Commissioner of Patents and Trademarks.	ents or copy thereof.		
	Name of conveying party(ies):	132590 receiving party(ies):		
	NAOYA HANEDA			
		Name: Sony Corporation		
	Additional name(s) of conveying party(ies) attached?	Internal Address:		
	Yes X No	Street Address: 7-35, Kitashinagawa 6-Chome		
-		City, State and Zip: <u>Shinagawa-ku, Tokyo, 141-0001</u>	JAPA	
	Nature of Conveyance:	Additional Name(s) & address(es) attached?		
	Assignment Merger	☐ Yes ☒ No		
]	Security Agreement Change of Name			
]	Other			
	Execution Date: <u>August 23, 1999</u>	8-30-99		
	Application number(s) or patent number(s):			
	If this document is being filed together with a new applica	ation, the execution date of the application is:		
	A. Patent Application No. 09/349,887	B. Patent No.(s)		
	B. Filed: July 8, 1999			
	Additional numbers attached?	Yes X No	_	
	Name and address of party to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved	: 1	
	Name: Charles P. Sammut	7. Total fee (37 CFR 3.41):\$ 40.00		
	Internal Address: Limbach & Limbach L.L.P. Street Address: 2001 Ferry Building City, State, ZIP: San Francisco, California 94111 Telephone: (415) 433-4150	X Enclosed Charge any deficiencies in the enclosed fee Deposit Account No. 12-1420 Authorized to be charged to deposit account	to	
	Facsimile: (415) 433-8716	8. Deposit account number: 12-1420		
	Attorney Docket No. SONY-P9787			
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	Statement and signature.			
	To the best of my knowledge and belief, the foregoing information is true at	d correct and any attached copy is a true copy of the original document		
	Charles P. Sammut, Reg. No. 28,901	Mm/. (August 27, 19	200	
	Name of Person Signing	Signature Date	777	
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	/1999 MTHAI1 0000015" 09349887			
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Docket Number: SONY-P9787

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in RECORDING APPARATUS AND METHOD, REPRODUCING APPARATUS AND METHOD,

AND RECORDING MEDIUM

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 09/349,887...., Filing Date:7/8/1999....

This assignment executed on the dates indicated below.

NAOYA HANEDA	
Name of first or sole inventor	Execution date of U.S. Patent Application
TOKYO, JAPAN Residence of first or sole inventor	
Mayd Aneda Signature of first or sole inventor	August 23, 1999
Signature of first or sole inventor	Date of this assignment

PATENT REEL: 010202 FRAME: 0113